

Product Information Sheet

EPO-TEK® P1011-2

Date:	February 2025	Recommended Cure: Pre-Bake: 80°C/30 Minutes (maximum)+
Rev:	I	Cure: 150°C/1 Hour (with or without vacuum)+
No. of Components:	Single	Post Cure: 285°C/90 Minutes
Mix Ratio by Weight:	N/A	
Specific Gravity:	2.39	
Pot Life:	N/A	Dry Time: 7 Days
Shelf Life- Bulk:	One year at room temperature	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® P1011-2 is a single component, modified polyimide, silver-filled adhesive designed for chip bonding in microelectronic and optoelectronic applications. This is a replacement for EPO-TEK® P1011.

Typical Properties: Cure condition: Pre-Bake: 80°C/30 Minutes (maximum) - Cure: 150°C/1 Hour (with or without vacuum) – Post-Cure: 285°C/90 Minutes Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:				
Color (before cure):	Silver			
Consistency:	Smooth paste			
Viscosity (23°C) @ 10 rpm:	9,714	cPs		
Thixotropic Index:	1.98			
Glass Transition Temp:	Not detected			
Coefficient of Thermal Expansion (CTE):	Below Tg:			
	Above Tg:			
Shore D Hardness:				
Lap Shear @ 23°C:				
Die Shear @ 23°C:		Kg	psi	
Degradation Temp:		°C		
Weight Loss:				
	@ 200°C:	%		
	@ 250°C:	%		
	@ 300°C:	%		
Suggested Operating Temperature:	< 300	°C (Intermittent)		
Storage Modulus:				
Particle Size:	≤ 20	microns		
ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:		W/mK		
Volume Resistivity @ 23°C:	0.0005	Ohm-cm		

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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